

Abstract of Disclosure

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A rotary drive device of a polishing device such as a polishing table, a table for CMP or a rotary drive device of a polisher which is used to flatten an end face of a semiconductor wafer or an end face of liquid crystal glass, wherein disposed is a traction drive type reduction gear, which comprises: an externally contacting shaft formed in a ring-shaped hollow cylinder and arranged at the center; a plurality of intermediate shafts which are equidistantly disposed at the circumference of the externally contacting shaft, and at least one of which is an input shaft; and an internally contacting cylinder with which the intermediate shafts internally contact, and under free conditions, the externally contacting shaft formed in a hollow cylinder has a diameter which is a little bit larger than a diameter of an imaginary circle which externally contacts with a plurality of intermediate shafts whereby pressing load is created by means of deformation of the hollow cylinder.

Fig. 1